



SOT617-1

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; 0.5 mm pitch, 5 mm x 5 mm x 0.85 mm body

12 July 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32
Package type industry code	HVQFN32
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	18-10-2002
Manufacturer package code	SOT617

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	-	0.85	1	mm
package height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	



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2 Package outline

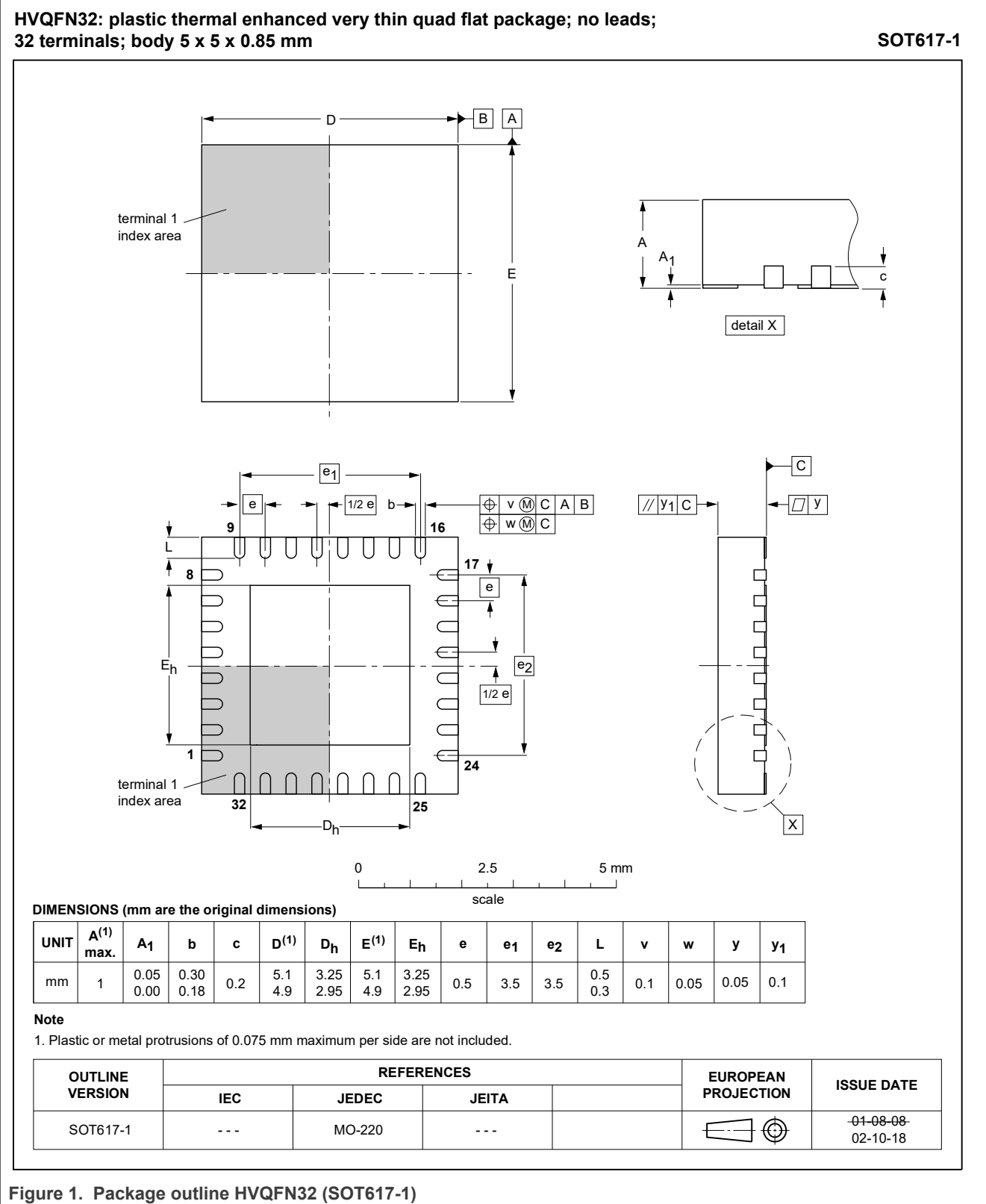


Figure 1. Package outline HVQFN32 (SOT617-1)

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3 Soldering

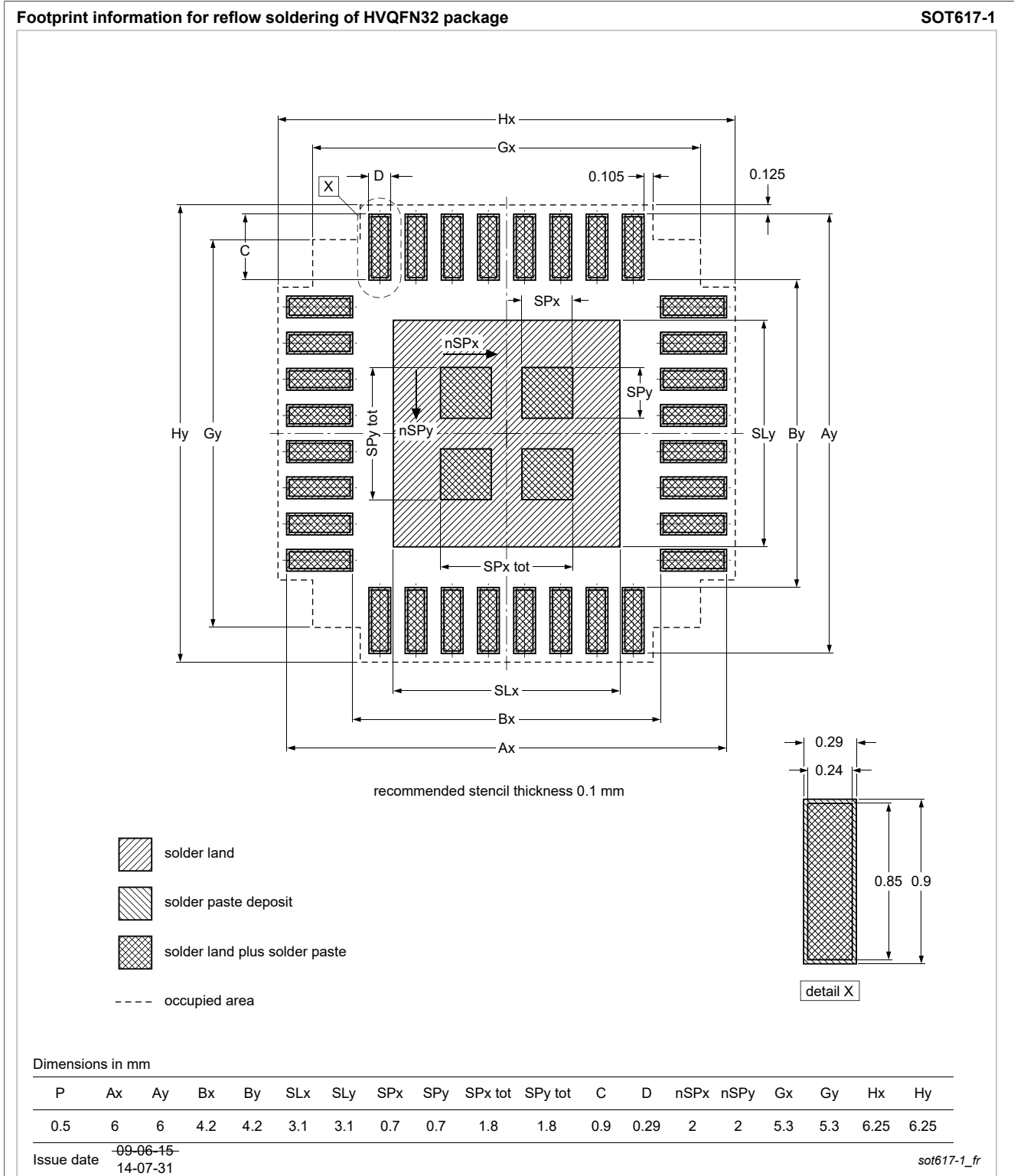


Figure 2. Reflow soldering footprint for HVQFN32 (SOT617-1)

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4 Legal information

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